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FIRST NAMED INVENTOR ATTORNEY DOCKET NO. CONFIRMATION NO. APPLICATION NO. FILING DATE 2023600-7006254001 07/18/2003 Vladimir A. Dmitriev 3202 10/623.375 EXAMINER 12/29/2004 SONG, MATTHEW J David G. Beck Bingham McCutchen, LLP PAPER NUMBER ART UNIT Three Embarcadero Center, 18th Floor San Francisco, CA 94111

1765 DATE MAILED: 12/29/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

# Attachment(s) 1) Notice of

- 1) Notice of References Cited (PTO-892)
- 2) L Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)
  Paper No(s)/Mail Date 9/15/2004.

4) 🔲	Interview Summary (PTO-413)
	Panas Na/a\/Mail Data

5) Notice of Informal Patent Application (PTO-152)

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#### **DETAILED ACTION**

### Double Patenting

1. The nonstatutory double patenting rejection is based on a judicially created doctrine grounded in public policy (a policy reflected in the statute) so as to prevent the unjustified or improper timewise extension of the "right to exclude" granted by a patent and to prevent possible harassment by multiple assignees. See *In re Goodman*, 11 F.3d 1046, 29 USPQ2d 2010 (Fed. Cir. 1993); *In re Longi*, 759 F.2d 887, 225 USPQ 645 (Fed. Cir. 1985); *In re Van Ornum*, 686 F.2d 937, 214 USPQ 761 (CCPA 1982); *In re Vogel*, 422 F.2d 438, 164 USPQ 619 (CCPA 1970); and, *In re Thorington*, 418 F.2d 528, 163 USPQ 644 (CCPA 1969).

A timely filed terminal disclaimer in compliance with 37 CFR 1.321(c) may be used to overcome an actual or provisional rejection based on a nonstatutory double patenting ground provided the conflicting application or patent is shown to be commonly owned with this application. See 37 CFR 1.130(b).

Effective January 1, 1994, a registered attorney or agent of record may sign a terminal disclaimer. A terminal disclaimer signed by the assignee must fully comply with 37 CFR 3.73(b).

2. Claims 1-18 and 21-34 are rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 1-27 of U.S. Patent No. 6,613,143. Although the conflicting claims are not identical, they are not patentably distinct from each other because US 6,613,143 claims a Ga source, where two portions of the source are heated to different temperatures (claims 1 and 21), which reads on applicants' first and second Group III sources. US 6,613,143 also claims a first and second growth zone and transferring a substrate between growth zones to grow portions of a GaN single crystal in each zone by reacting the halide metal compound with a reaction gas (claim 1, 6 and 21). US 6,613,143 also claims introducing a halide reaction gas into the first source zone to form a halide metal compound (claim 1), this reads on applicants' reacting the source with a halide gas.

US 6,613,143 does not claim transferring the substrate to the second growth zone, wherein the temperature corresponding to the substrate varies by less than 200°C during the

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transferring step. It would have been obvious to a person of ordinary skill in the art at the time of the invention to modify US 6,613,143 by minimize any temperature fluctuations during the transfer step to less than 200°C to maintain the temperature of the substrate close to the deposition temperature to prevent the need to reheat the substrate to the deposition temperature and because temperature fluctuations during growth processes are known to be undesirable in regard to yield.

3. Claims 1-18 and 21-34 are rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 1-35 of U.S. Patent No. 6,573,164. Although the conflicting claims are not identical, they are not patentably distinct from each other because US 6,573,164 claims in claims 1 and 35:

locating a first Group III metal in a first source zone of a HVPE reactor,

locating a second Group III source within the reactor;

heating the first and second Group III metal to different temperatures;

heating a growth zone to a first temperature;

introducing a halide reaction gas to the first zone to form a Group III metal halide;

transporting the first Group III metal halide compound to the growth zone;

transporting a reaction gas into the growth zone;

growing a first layer by reacting the Group III metal halide compound with the reaction

gas;

transferring the substrate to a growth interruption zone, wherein temperature is within 50°C of the first temperature, this reads on applicants' transferring the substrate to a growth

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zone, wherein a substrate temperature varies by less than 200°C during transferring because the temperature of the interruption zone is close to the growth zone temperature;

introducing a halide reaction gas to the second zone to form a Group III metal halide; transporting the second Group III metal halide compound to the growth zone; transporting a reaction gas into the growth zone;

transporting the substrate from the growth interruption zone to the growth zone;

growing a second layer by reacting the Group III metal halide compound with the reaction gas.

US 6,573,164 claims a single growth zone. US 6,573,164 does not claim a second growth zone, wherein the first and second growth zones are different growth zones. It would have been obvious to a person of ordinary skill in the art at the time of the invention to modify US 6,573,164 by adding a second growth zone because duplication of parts is held to be obvious (MPEP 2144.04).

Referring to claim 2-3, US 6,573,164 claims a interruption zone and inert gas flow (claim 1).

Referring to claims 4-5, US 6,573,164 claims stabilizing the reaction (claim 3).

Referring to claim 6-8, US 6,573,164 claims maintaining the interruption zone within the claim range, which will prevent the temperature of the substrate from varying during the transferring step.

Referring to claim 9-11, US 6,573,164 is silent to the thickness of the deposited layer.

Thickness of the deposited layer is a matter of design choice and is within the skill of an ordinary person skilled in the art.

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Referring to claim 12-14, US 6,573,164 claims inert gas flow angles (claim 8-10).

Referring to claim 15-18, US 6,573,164 claims additional sources (claim 25-34).

Referring to claim 21-34, US 6,573,164 claims transferring impurity metal (claim 15-24).

4. Claims 19-20 are rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 1-35 of U.S. Patent No. 6,573,164 in view of Kiyoku et al (US 6,153,010). US 6,573,164 teaches all of the limitations of claim 19, as discussed previously, except US 6,573,164 does not teach growing a buffer layer prior to growing the first layer.

In a method of growing nitride semiconductors, note entire reference, Kiyoku et al teaches a buffer layer 12 of a single layer structure and the buffer layer eases the lattice mismatch between the dissimilar substrate 11 and the nitride semiconductor grown on the buffer layer 12. Kiyoku et al also teaches the buffer layer is made of undoped GaN and the nitride semiconductor is made of  $Al_xGa_{1-x}N$  ( $0 \le x \le 0.5$ ). Kiyoku et al also teaches the underlayer and nitride semiconductor can be made by HVPE (col 5, ln 1-35 and col 9, ln 55-60). It would have been obvious to a person of ordinary skill in the art at the time of the invention to modify US 6,573,164 with Kiyoku et al's buffer layer to reduce lattice mismatch between the substrate and nitride semiconductor.

Claims 1-18 and 21-34 are rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 1-35 of U.S. Patent No. 6,573,164 in view of U.S. Patent No. 6,613,143.

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US 6,573,164 teaches all of the limitations of claim 19, as discussed previously, except US 6,573,164 claims a single growth zone. US 6,573,164 does not claim a second growth zone, wherein the first and second growth zones are different growth zones.

US 6,613,143 claims a Ga source, where two portions of the source are heated to different temperatures (claims 1 and 21), which reads on applicants' first and second Group III sources. US 6,613,143 also claims a first and second growth zone and transferring a substrate between growth zones to grow portions of a GaN single crystal in each zone by reacting the halide metal compound with a reaction gas (claim 1, 6 and 21). US 6,613,143 also claims introducing a halide reaction gas into the first source zone to form a halide metal compound (claim 1), this reads on applicants' reacting the source with a halide gas. It would have been obvious to a person of ordinary skill in the art at the time of the invention to modify US 6,573,164 with US 6,613,143 second growth zone to grow a second layer at a different growth rate.

Claims 19-20 are rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 1-35 of U.S. Patent No. 6,573,164 in view of U.S. Patent No. 6,613,143, as applied to claims 1-18 and 21-34 above, and further in view of Kiyoku et al (US 6,153,010). The combination of US 6,573,164 and US 6,573,164 teaches all of the limitations of claim 19, as discussed previously, except the combination of US 6,573,164 and US 6,573,164 does not teach growing a buffer layer prior to growing the first layer.

In a method of growing nitride semiconductors, note entire reference, Kiyoku et al teaches a buffer layer 12 of a single layer structure and the buffer layer eases the lattice

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mismatch between the dissimilar substrate 11 and the nitride semiconductor grown on the buffer layer 12. Kiyoku et al also teaches the buffer layer is made of undoped GaN and the nitride semiconductor is made of  $Al_xGa_{1-x}N$  (0 $\leq x\leq 0.5$ ). Kiyoku et al also teaches the underlayer and nitride semiconductor can be made by HVPE (col 5, ln 1-35 and col 9, ln 55-60). It would have been obvious to a person of ordinary skill in the art at the time of the invention to modify the combination of US 6,573,164 and US 6,573,164 with Kiyoku et al's buffer layer to reduce lattice mismatch between the substrate and nitride semiconductor.

#### Conclusion

5. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Matthew J Song whose telephone number is 571-272-1468. The examiner can normally be reached on M-F 9:00-5:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nadine Norton can be reached on 571-272-1465. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

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MJS

December 22, 2004

Matthew J Song Examiner

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ROBERT KUNEMUND PRIMARY EXAMINER